

DESCRIPTION

The fundamental of SP6002 synchronous rectifier (SR) driver IC is based on our U.S. patented methods that utilize the principle of "prediction" logic circuit. The IC deliberates previous cycle timing to control the SR in present cycle by "predictive" algorithm that makes adjustments to the turn-off time, in order to achieve maximum efficiency and avoid cross-conduction at the same time. It also maintains the MOSFET's body diode conduction at minimum level. The SP6002 is capable to adapt in almost all existing forward converters with few adjustments considered necessary.

FEATURES

- Offers 4 to 8% efficiency improvement over Schottky Diodes (depend on drive configuration of the SR).
- Drives all logic level Power MOSFET.
- Prediction gate timing control.
- Minimum MOSFET body diode conduction.
- Operating frequency up to 650 KHz.
- Synchronize to transformer secondary voltage waveform.

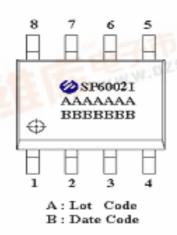
APPLICATIONS

- Servers & workstations
- Storage area network power supplies
- Telecommunication converters
- Embedded systems
- Industrial & commercial systems using high current processors

PIN CONFIGURATION (SOP-8)



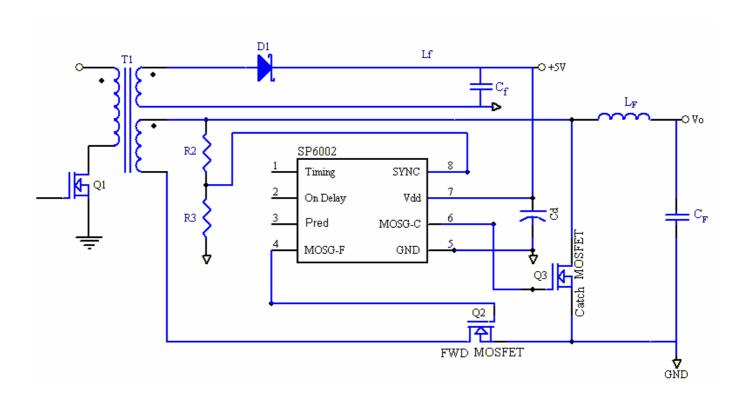
PART MARKING







TYPICAL APPLCATION CIRCUIT

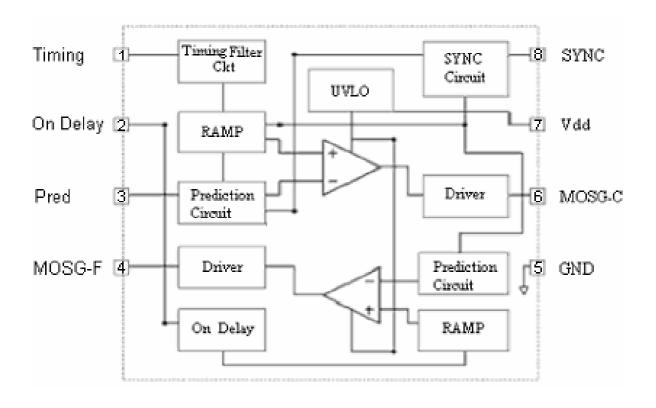


PIN DESCRIPTION

Pin	Symbol	Description		
1	Timing	Discontinuous current filter timing adjustment resistor connection.		
2	On Delay	Imposed delay between Catch gate turn OFF and Forward gate turn ON.		
3	Pred	Capacitor to store previous cycle timing for Catch MOSFET		
4	MOSG-F	Forward MOSFET gate drive.		
5	GND	Ground connection.		
6	MOSG-C	Catch MOSFET gate drive.		
7	Vdd	DC supply voltage.		
8	SYNC	Synchronized signal from transformer's output.		



BLOCK DIAGRAM



ORDERING INFORMATION

Part Number	Package	Part Marking
SP6002S8RG	SOP-8	SP6002 I
SP6002S8TG	SOP-8	SP6002 I

※ SP6002S8RG: 7" Tape Reel; Pb − Free

※ SP6002S8TG: Tube; Pb − Free

ABSOULTE MAXIMUM RATINGS (T_A=25°C, unless otherwise specified.)

The following ratings designate persistent limits beyond which damage to the device may occur.

Symbol	Parameter	Value	Unit
V_{dd}	DC Supply Voltage	7	V
V _{SYNC}	SYNC Voltage	7.5	V
I _{OUT}	Peak Source Current (Pulsed)	1	A
	Peak Sink Current (Pulsed)	1.5	A
P_{D}	Power Dissipation @ $T_A=85^{\circ}C$ (*)	0.25	W
$T_{\rm J}$	Operating Junction Temperature Range	-40 to 150	$^{\circ}\mathbb{C}$
T_{STG}	Storage Temperature Range	-40 to 150	$^{\circ}\mathbb{C}$
T_{LEAD}	Lead Soldering Temperature for 5 sec.	260	$^{\circ}\mathbb{C}$



THERMAL RESISTANCE

Symbol	Parameter	Value	Unit
$R_{\Theta JC}$	Thermal Resistance Junction – Case (*)	45	°C/W

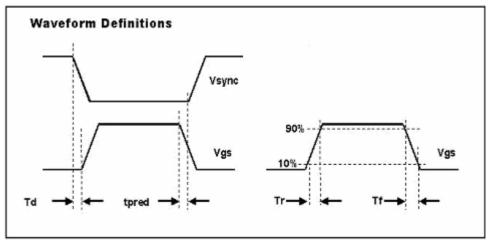
^(*) The power dissipation and thermal resistance are evaluated under copper board mounted with free air conditions.

ELECTRICAL CHARACTERISTICS

 $(T_A=25^{\circ}\text{C}, V_{dd}=5\text{V}, V_{SYNC}=5\text{V}, Freq. =300 \text{ KHz}, Duty Cycle=50\%, unless otherwise specified.})$

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit		
SUPPLY INPUT								
Idd	Supply current	No load	4	5.5	8	mA		
Vonth	Vdd turn on threshold(*)			5.0	7.0	V		
Voffth	Vdd turn off threshold		3.8	4.1		V		
SYNC REFI	ERENCE (SYNC)							
Vshth	SYNC high voltage		3.9	5.0		V		
Vslth	SYNC low voltage			0.9	1.2	V		
MOSFET G	ATE DRIVER (MOSG-C & MOSG-F)							
Voh	Output high voltage	Io = -200 mA	4.8	4.9	5.0	V		
Vol	Output low voltage	Io = 200mA	0.0	0.1	0.2	V		
Td	Propagation delay	No load	15	20	25	ns		
Tr	Rise time	Load = 1nF (**)	24	28	36	ns		
Tf	Fall time	Load = 1nF(**)	20	23	30	ns		
Tpred	Delay time	No load		100		ns		

^(*) We have build in a diode from SYNC(pin8) to VDD(pin7).



Vgs = MOSG-C Output

^(**) Tr & Tf are measured among 10% and 90% of starting and final voltage.



PERFORMANCE CHARACTERISTICS (T_A=25°C, unless otherwise specified.)

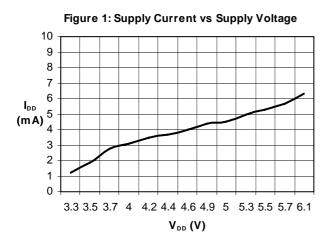
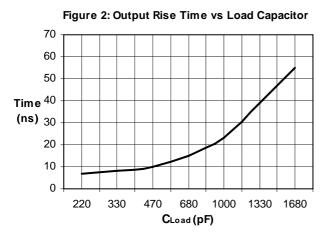
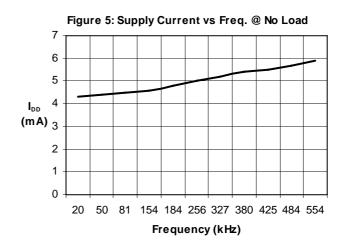
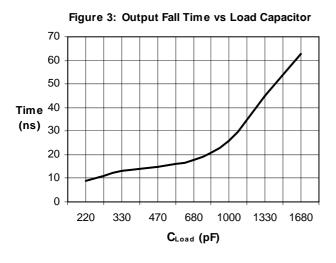
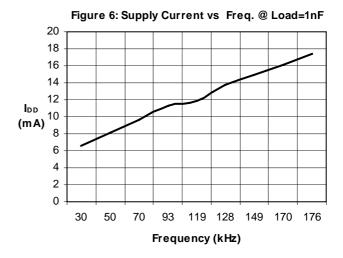


Figure 4: Supply Current vs Load Capacitor 20 18 16 14 12 I_{DD} 10 (m A) 8 6 4 2 0 220 330 470 680 1000 1560 2200 2530 2880 C_{Load} (pF)



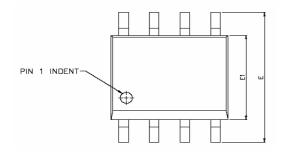


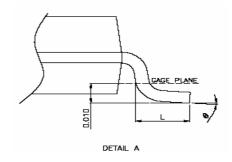


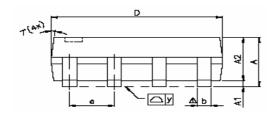


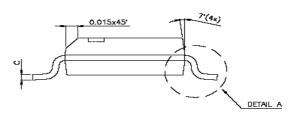


SOP-8 PACKAGE OUTLINE









CV4/DOLC	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
SYMBOLS	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.47	1.60	1.73	0.058	0.063	0.068
A1	0.10		0.25	0.004		0.010
A2		1.45			0.057	
Ь	0.33	0.41	0.51	0.013	0.016	0.020
С	0.19	0.20	0.25	0.0075	0.008	0.0098
D	4.80	4.85	4.95	0.189	0.191	0.195
Е	5.80	6.00	6.20	0.228	0.236	0.244
E1	3.80	3.90	4.00	0.150	0.154	0.157
е	_	1.27			0.050	
L	0.38	0.71	1.27	0.015	0.028	0.050
<u>∕</u> 2 y			0.076			0.003
0	0,		8*	0,		8.



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